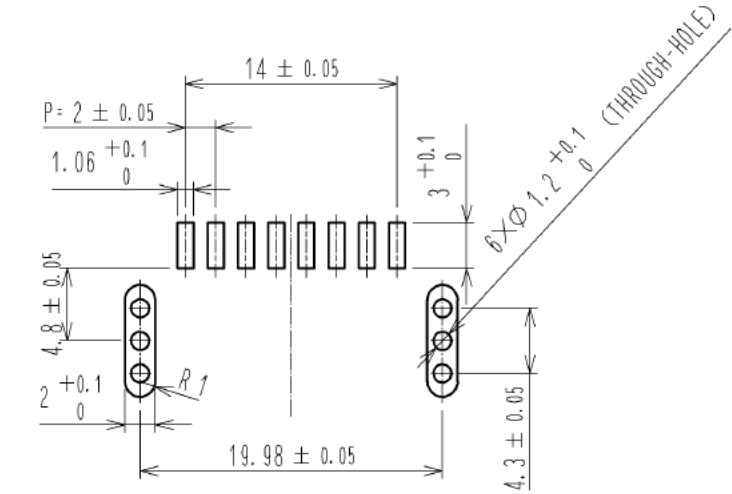
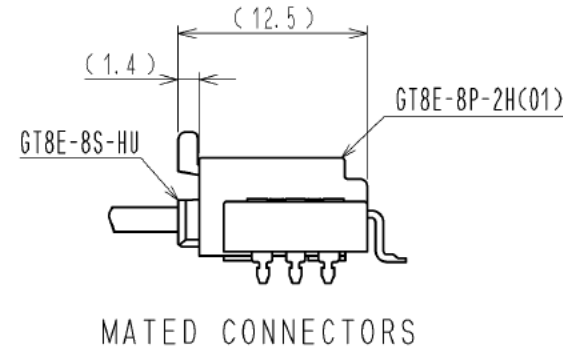
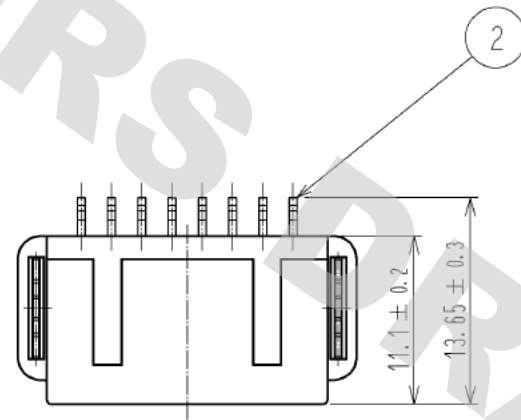
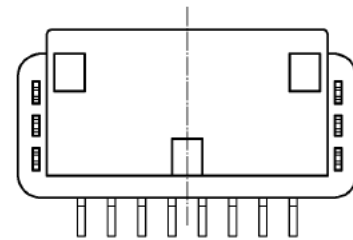
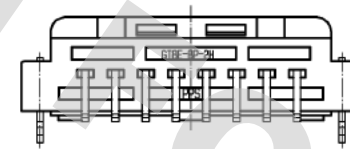
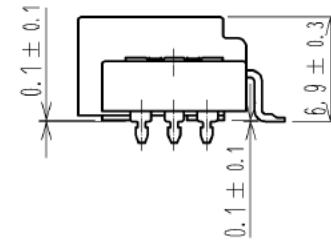
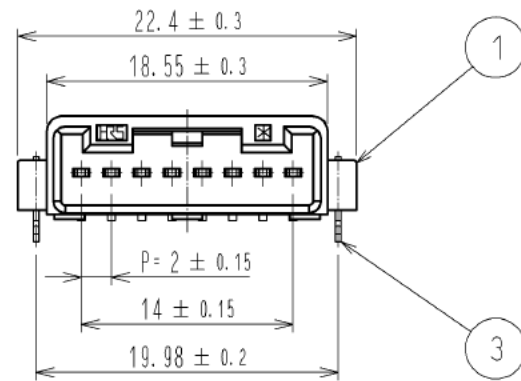


DRAWING FOR REFERENCE: This is subject to change without notice
05/31/2013

ELV. RoHS COMPLIANT



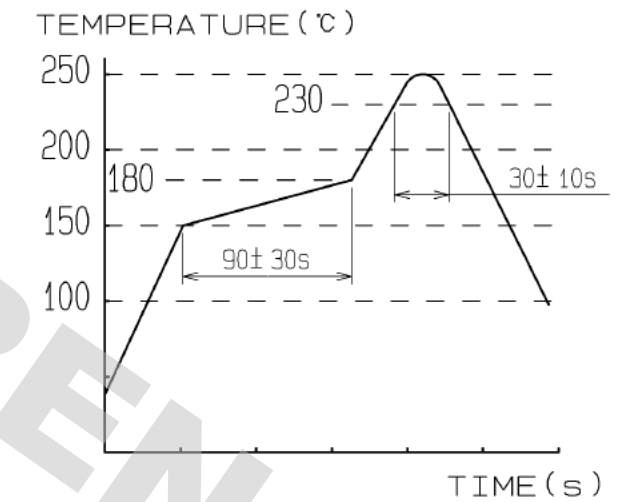
RECOMMENDED PC BOARD PATTERN



NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR
REFLOW (REFER TO RIGHT FIG.)
REFLOW HEATING METHODS: FAR-INFLARED, IN THE
AIR OR NITROGEN

REFLOW No.: MAX 2TIMES
PEAK TEMPERATURE: 250°C
ABOVE 230°C: 20~40s
PREHEAT: 150~180°C
60~120s

2. SOLDERING TEMPERATURE: 280~300°C, MAX 2s
3. COPLANARITY OF LEADS SHALL BE UNDER 0.1mm.
4. RECOMMENDED THICKNESS FOR PC BOARD IS 1.6mm.
5. RECOMMENDED THICKNESS FOR SOLDER PASTE IS 0.15mm.



2	BRASS	LEAD:TIN-COPPER ALLOY PLATING CONTACT:GOLD PLATING	3	BRASS	TIN-COPPER ALLOY PLATING
1	PPS	BLACK			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED CHECKED DATE
HIROSE ELECTRIC CO., LTD.		APPROVED : NH. NAKATA	13.03.19	DRAWING NO.	EDC3-167882-01
		CHECKED : NH. NAKATA	13.03.19	PART NO.	GT8E-8P-2H(01)
		DESIGNED : RZ. KANO	13.03.19	CODE NO.	CL758-1006-7-01
		DRAWN : RZ. KANO	13.03.19		